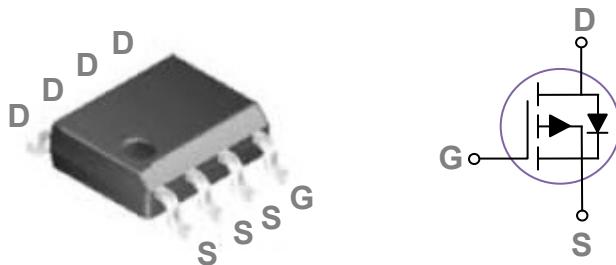


General Description

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

SOP8 Pin Configuration



| BVDSS | RDS(ON) | ID |
|-------|---------|------|
| -20V | 8.5mΩ | -14A |

Features

- -20V, -14A, RDS(ON) = 8.5mΩ@VGS = -4.5V
- Improved dv/dt capability
- Fast switching
- Green Device Available
- Suit for -1.8V Gate Drive Applications

Applications

- Notebook
- Load Switch
- Networking
- Hand-Held Instruments

Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Rating | Units |
|-----------|--|------------|-------|
| V_{DS} | Drain-Source Voltage | -20 | V |
| V_{GS} | Gate-Source Voltage | ± 12 | V |
| I_D | Drain Current – Continuous ($T_c=25^\circ\text{C}$) | -14 | A |
| | Drain Current – Continuous ($T_c=100^\circ\text{C}$) | -8.8 | A |
| I_{DM} | Drain Current – Pulsed ¹ | -56 | A |
| P_D | Power Dissipation ($T_c=25^\circ\text{C}$) | 2 | W |
| | Power Dissipation – Derate above 25°C | 0.016 | W/°C |
| T_{STG} | Storage Temperature Range | -55 to 150 | °C |
| T_J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|------|
| $R_{\theta JA}$ | Thermal Resistance Junction to ambient | --- | 62 | °C/W |
| $R_{\theta JC}$ | Thermal Resistance Junction to Case | --- | 17 | °C/W |

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)
Off Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|--|--|---|------|-------|-----------|---------------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{\text{GS}}=0\text{V}$, $I_D=-250\mu\text{A}$ | -20 | --- | --- | V |
| $\Delta \text{BV}_{\text{DSS}}/\Delta T_J$ | BV_{DSS} Temperature Coefficient | Reference to 25°C , $I_D=-1\text{mA}$ | --- | -0.01 | --- | $\text{V}/^\circ\text{C}$ |
| I_{DSS} | Drain-Source Leakage Current | $V_{\text{DS}}=-20\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$ | --- | --- | -1 | μA |
| | | $V_{\text{DS}}=-16\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$ | --- | --- | -10 | μA |
| I_{GSS} | Gate-Source Leakage Current | $V_{\text{GS}}=\pm 12\text{V}$, $V_{\text{DS}}=0\text{V}$ | --- | --- | ± 100 | nA |

On Characteristics

| | | | | | | |
|---------------------|-----------------------------------|---|------|------|------|------------------|
| $R_{\text{DS(ON)}}$ | Static Drain-Source On-Resistance | $V_{\text{GS}}=-4.5\text{V}$, $I_D=-8\text{A}$ | --- | 6.5 | 8.5 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=-2.5\text{V}$, $I_D=-5\text{A}$ | --- | 9 | 12 | |
| | | $V_{\text{GS}}=-1.8\text{V}$, $I_D=-3\text{A}$ | --- | 12 | 17 | |
| $V_{\text{GS(th)}}$ | Gate Threshold Voltage | $V_{\text{GS}}=V_{\text{DS}}$, $I_D = -250\mu\text{A}$ | -0.3 | -0.6 | -1.0 | V |
| g_{fs} | Forward Transconductance | $V_{\text{DS}}=-10\text{V}$, $I_S=-5\text{A}$ | --- | 20 | --- | S |

Dynamic and switching Characteristics

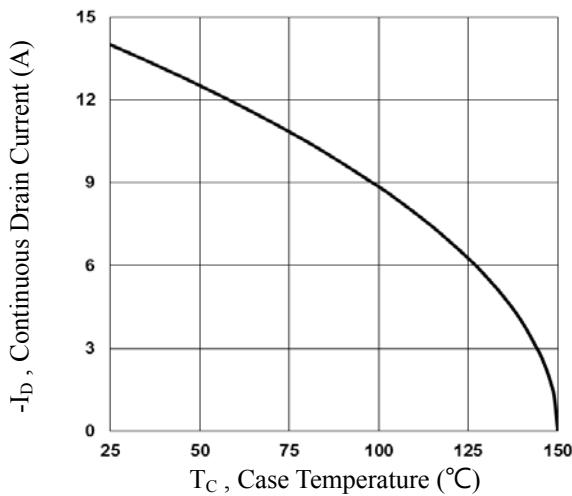
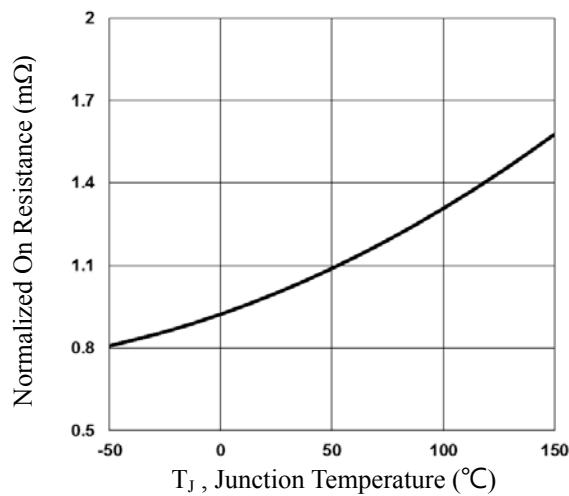
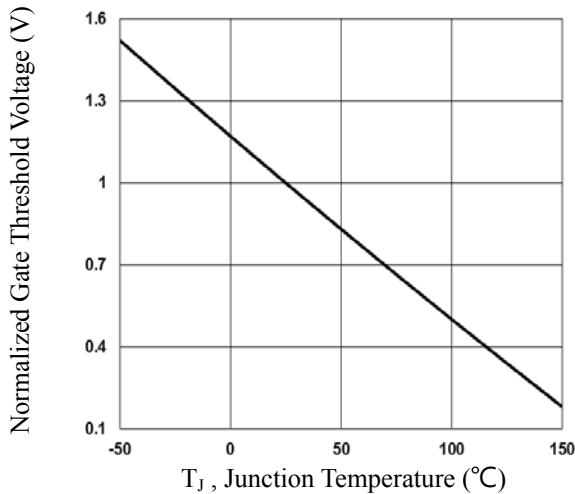
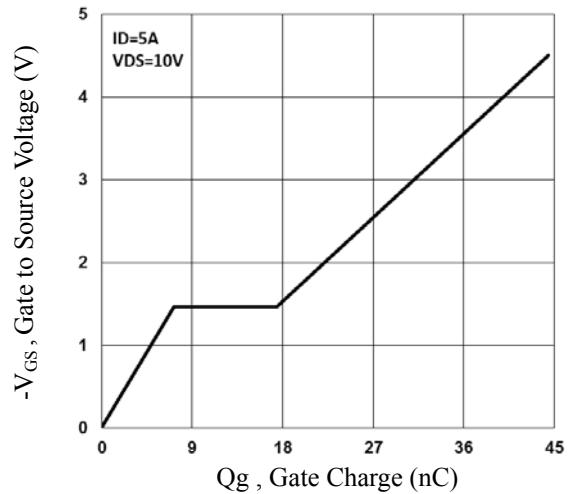
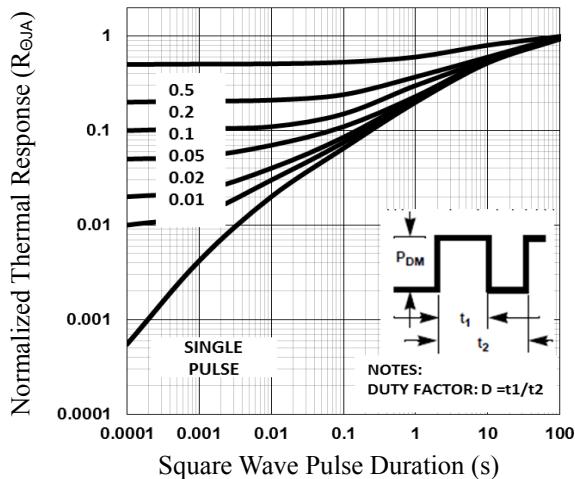
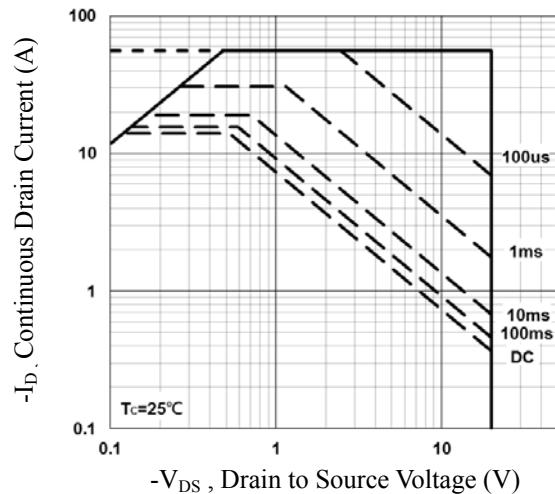
| | | | | | | |
|---------------------|------------------------------------|---|-----|------|------|----|
| Q_g | Total Gate Charge ^{2,3} | $V_{\text{DS}}=-10\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $I_D=-5\text{A}$ | --- | 44.4 | 80 | nC |
| Q_{gs} | Gate-Source Charge ^{2,3} | | --- | 7.2 | 14 | |
| Q_{gd} | Gate-Drain Charge ^{2,3} | | --- | 10.2 | 20 | |
| $T_{\text{d(on)}}$ | Turn-On Delay Time ^{2,3} | $V_{\text{DD}}=-10\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $R_G=25\Omega$ $I_D=-1\text{A}$ | --- | 13.2 | 26 | nS |
| T_r | Rise Time ^{2,3} | | --- | 68 | 120 | |
| $T_{\text{d(off)}}$ | Turn-Off Delay Time ^{2,3} | | --- | 160 | 320 | |
| T_f | Fall Time ^{2,3} | | --- | 154 | 300 | |
| C_{iss} | Input Capacitance | $V_{\text{DS}}=-15\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$ | --- | 4060 | 8000 | pF |
| C_{oss} | Output Capacitance | | --- | 520 | 1000 | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 400 | 800 | |

Drain-Source Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|---------------------------|---|------|------|------|------|
| I_s | Continuous Source Current | $V_G=V_D=0\text{V}$, Force Current | --- | --- | -14 | A |
| I_{SM} | Pulsed Source Current | | --- | --- | -28 | A |
| V_{SD} | Diode Forward Voltage | $V_{\text{GS}}=0\text{V}$, $I_s=-1\text{A}$, $T_J=25^\circ\text{C}$ | --- | --- | -1 | V |

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.


Fig.1 Continuous Drain Current vs. T_C

Fig.2 Normalized RDS(ON) vs. T_J

Fig.3 Normalized V_{th} vs. T_J

Fig.4 Gate Charge Waveform

Fig.5 Normalized Transient Response

Fig.6 Maximum Safe Operation Area

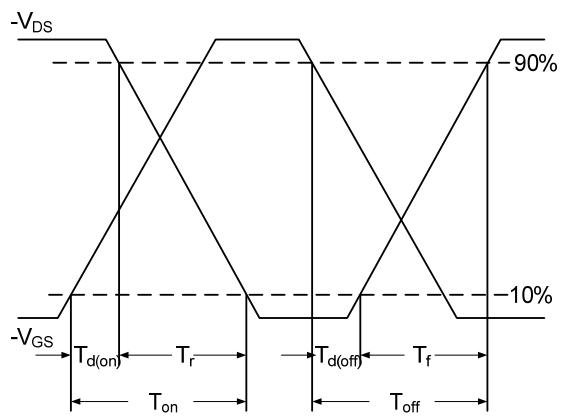


Fig.7 Switching Time Waveform

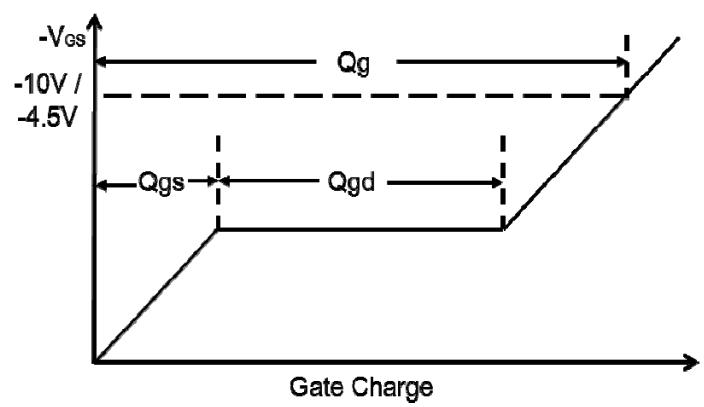
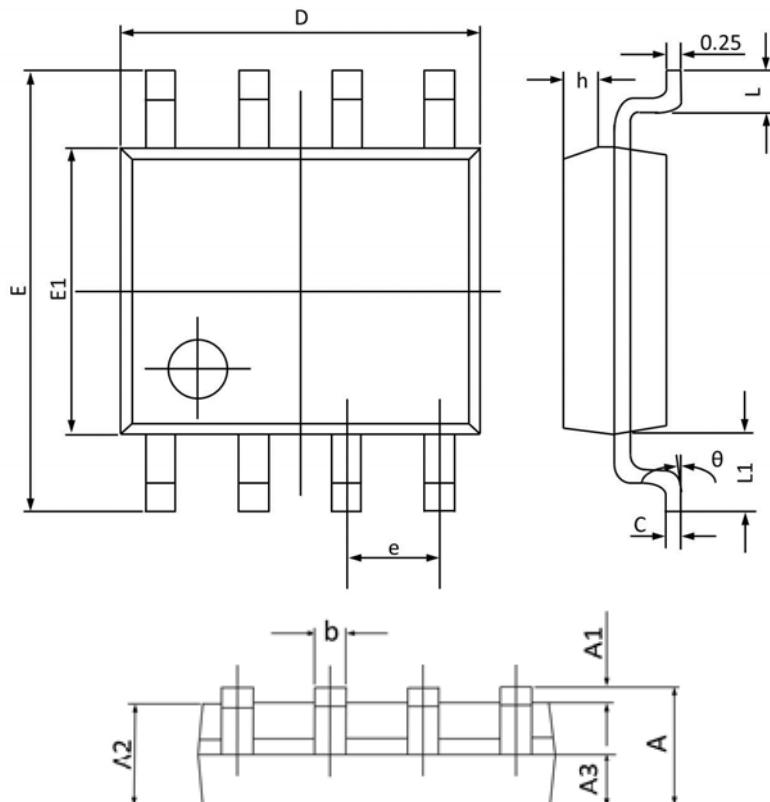


Fig.8 Gate Charge Waveform

SOP8 PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 1.350 | 1.750 | 0.053 | 0.068 |
| A1 | 0.100 | 0.250 | 0.004 | 0.009 |
| A2 | 1.300 | 1.500 | 0.052 | 0.059 |
| A3 | 0.600 | 0.700 | 0.024 | 0.027 |
| b | 0.390 | 0.480 | 0.016 | 0.018 |
| c | 0.210 | 0.260 | 0.009 | 0.010 |
| D | 4.700 | 5.100 | 0.186 | 0.200 |
| E | 5.800 | 6.200 | 0.229 | 0.244 |
| E1 | 3.700 | 4.100 | 0.146 | 0.161 |
| e | 1.270(BSC) | | 0.050(BSC) | |
| h | 0.250 | 0.500 | 0.010 | 0.019 |
| L | 0.500 | 0.800 | 0.019 | 0.031 |
| L1 | 1.050(BSC) | | 0.041(BSC) | |
| θ | 0° | 8° | 0° | 8° |